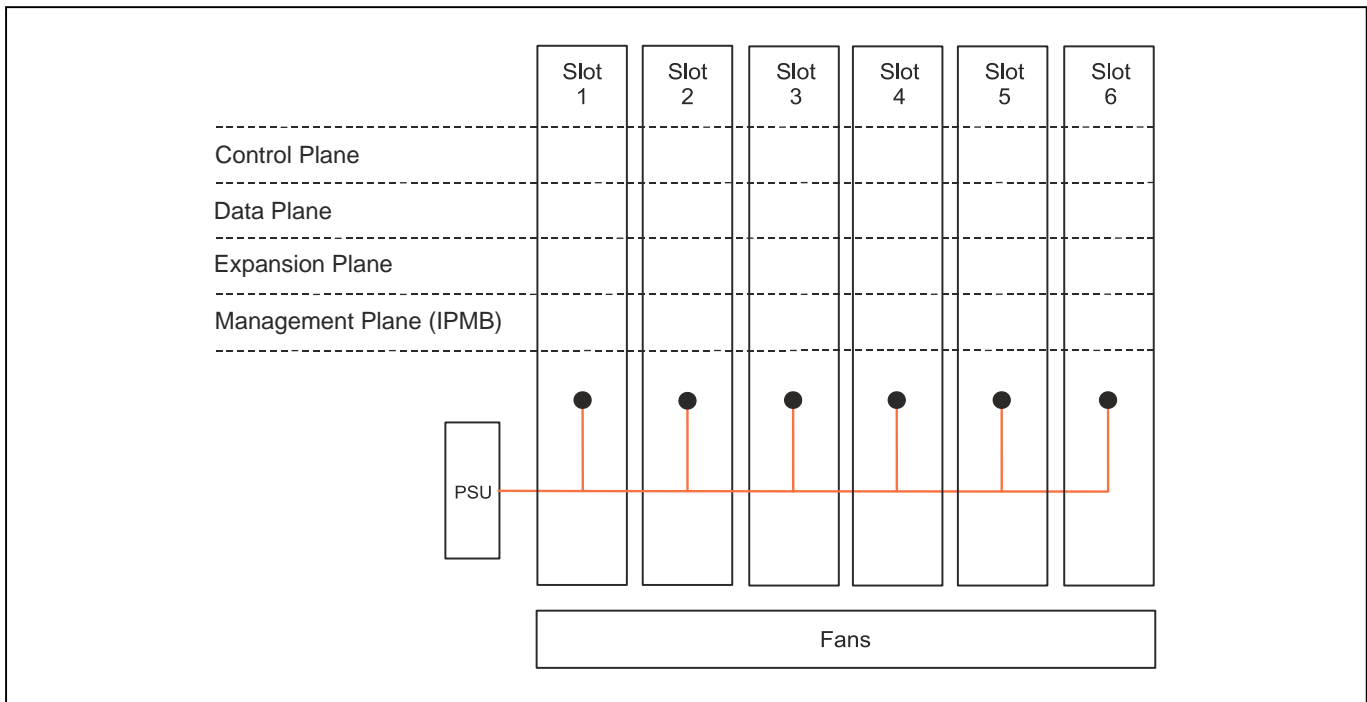
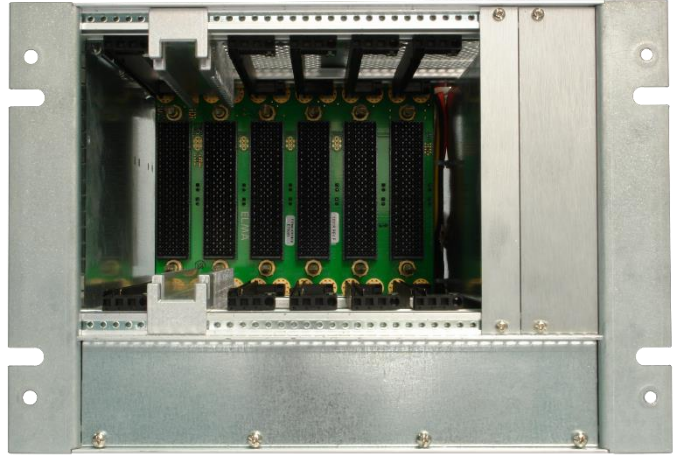


6-Slot 3U VPX™ Power and Ground System

Key Features

SY TR3/526 is a ready-to-use solution for customers starting VPX™ projects based on Intel® processor boards.

- Based on popular 3U VPX form factor
- Supplied with built in AC power supply, power and ground backplane with one Meritec® cable and cooling fans
- Six slots for processor and peripheral boards
- No pre-assigned fabric connections on the backplane – all connections between VPX boards are made with Meritec® cables



3U VPX Development System

- 3U VPX™ Development System:
 - 6 vertically mounted 3U VPX slots
 - cooling air intake at the bottom of the system
 - air exhaust at top of the system
- VPX backplane provides:
 - 6 x slots
- Meritec® 6-inch Fat Pipe Cable:
 - allows connections between modules
 - supports PCI Express® Gen 3 or 10GBASE-KR connectivity
- Meritec® rear housing and deployment kits to provide retention for Meritec® cables
- contact your local Concurrent Technologies sales office for further details on board options

Power Supply

- integrated 300W modular power supply:
 - +12V output (18A max)
 - -12V output (3A max)
 - +5V output (35A max, 0A min.)
 - +3.3V output (28A max, 0A min.)
 - rated power 300 Watt
 - AC 90-264V, 47Hz to 63Hz input

Environmental Specification

- operating temperatures:
 - +5°C to +40°C (operating)
 - -25°C to +65°C (non-operating)
- relative humidity, non-condensing:
 - 20% to 90% (operating)
 - 5% to 90% (non-operating)

Mechanical Specification

- chassis is less than 14.3lbs (6.5kg)
- 5HP (1.0-inch) backplane slot pitch supports:
 - 0.8-inch and 1.0-inch width boards
 - IEEE 1101.10 as per VITA 46.0
- chassis dimensions:
 - total chassis height is 4U
 - width 8.4-inch (214mm) x depth 11.5-inch (292mm)

Safety

- PCBs (PWB) manufactured with flammability rating of UL94V-0

Optional Accessories

- Meritec® 6-inch Fat Pipe Cable:
 - allows connections between modules
 - supports PCI Express® Gen 3 or 10GBASE-KR connectivity
- Conduction-cooled card guides:
 - allows use of conduction-cooled modules in combination with air-cooled modules